

subjacent to the multilayer ceramic substrate.

28. (Amended) A method for making a substrate to package a die, the method comprising:

forming a first portion of the substrate using ceramic materials, the first portion comprising at least one capacitor having first and second terminals;

forming a second portion of the substrate using organic materials, the second portion comprising a plurality of conductors therein, including a first conductor coupled to the first terminal and a second conductor coupled to the second terminal; and

forming a first plurality of lands on a surface of the second portion of the substrate, including a first land coupled to the first conductor, and a second land coupled to the second conductor, wherein the first and second lands are positioned to couple [be coupled] to first and second power supply nodes of the die.

29. (Amended) The method recited in claim 28, wherein forming the first portion comprises forming a first signal node, wherein forming the second portion comprises forming a third conductor coupled to the first signal node, and wherein forming the first plurality of lands comprises forming a third land coupled to the third conductor, the third land being positioned to couple [be coupled] to a signal node of the die.

**REMARKS**

Claims 1, 4, 6, 28, and 29 have been amended for clarity. Claims 11-27, which the Examiner restricted to Groups II and III, have been canceled without prejudice. As a result of this amendment, claims 1-10 and 28-30 are pending in this application.

The Examiner is invited to contact Applicants' representative, Walter W. Nielsen at 602/298-8920 or the below signed attorney if there are any questions regarding this Preliminary Amendment or if prosecution of this application may be assisted thereby.